# **Specification of Thermoelectric Module**

TEC1-19940

## **Description**

The 199 couples, 62 mm × 62 mm size single module which is made of our high performance ingot to achieve superior cooling performance and 70 °C or larger delta T max, is designed for superior cooling and heating applications. Beyond the standard below, we can design and manufacture the custom made module according to your special requirements.

#### Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

# **Application**

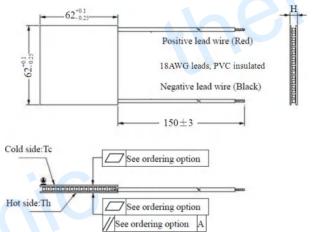
- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

## **Performance Specification Sheet**

| Th (°C)                    | 27    | 50    | Hot side temperature at environment: dry air, N <sub>2</sub>  |
|----------------------------|-------|-------|---|
| DT <sub>max</sub> (°C)     | 70    | 79    | Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side |
| U <sub>max</sub> (Voltage) | 25.0  | 26.6  | Voltage applied to the module at DT <sub>max</sub>  |
| I <sub>max</sub> (Amps)    | 40    | 40    | DC current through the modules at DT <sub>max</sub>   |
| Q <sub>Cmax</sub> (Watts)  | 627.9 | 680.4 | Cooling capacity at cold side of the module under DT=0 °C   |
| AC resistance (Ohms)       | 0.49  | 0.53  | The module resistance is tested under AC  |
| Tolerance (%)              | ± 10  |       | For thermal and electricity parameters  |

#### Geometric Characteristics Dimensions in millimeters

# **Manufacturing Options**



Thickness

H/(mm)

 $0:3.8\pm0.1$ 

 $1:3.8\pm0.05$ 

Suffix

TF

TF

A. Solder: B. Sealant:

1. T100: BiSn (Tmelt=138°C) 1. NS: No sealing (Standard)

2. T200: CuAgSn (Tmelt = 217°C) 2. SS: Silicone sealant

3. T240: SbSn (Tmelt =  $240^{\circ}$ C) 3. EPS: Epoxy sealant

C. Ceramics: D. Ceramics Surface Options:

1. Alumina (Al<sub>2</sub>O<sub>3</sub>, white 96%) 1. Blank ceramics (not metalized)

2. Aluminum Nitride (AlN) 2. Metalized

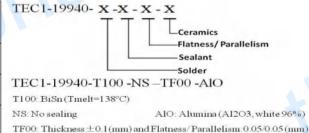
# **Ordering Option**

# Flatness/ Lead wire length (mm) Parallelism (mm) Standard/Optional length 0:0.12/0.12 150±3/Specify

Eg. TF00: Thickness 3.8±0.1(mm) and Flatness 0.012/0.012(mm)

1:0.06/0.06

# Naming for the Module



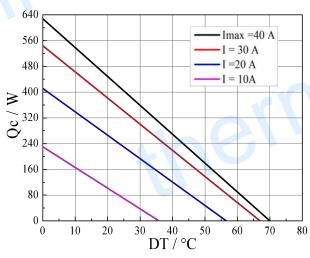
150±3/Specify

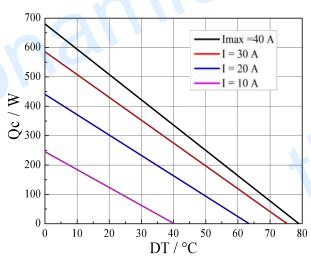
# **Specification of Thermoelectric Module**

## **TEC1-19940**

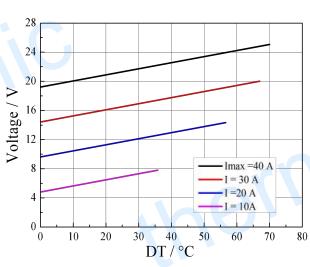


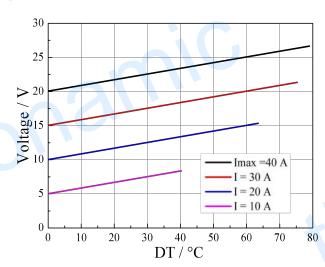
# Performance Curves at Th=50 °C



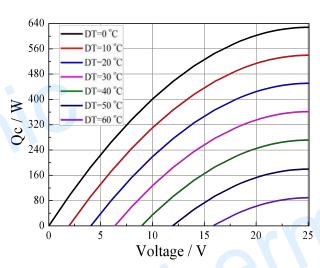


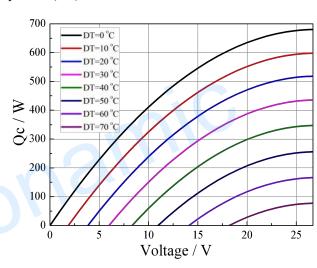
Standard Performance Graph Qc= f(DT)





Standard Performance Graph V= f(DT)





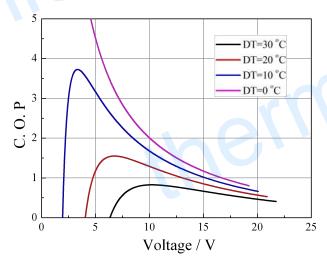
Standard Performance Graph Qc = f(V)

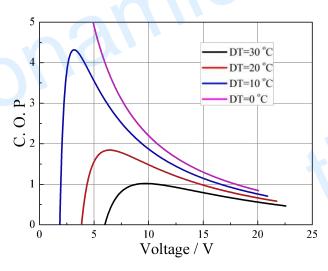
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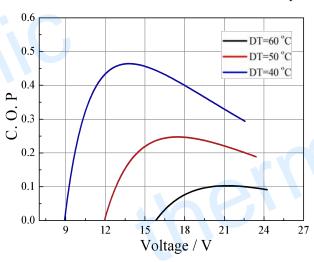
# Performance Curves at Th=27 °C

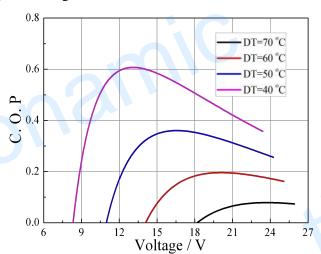
#### Performance Curves at Th=50 °C





Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C





Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power (V  $\times$  I).

# **Operation Cautions**

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating.
- Operation below I<sub>max</sub> or V<sub>max</sub>
- Work under DC